

REMARKS

The Office Action of January 10, 2006 has been received and its contents carefully considered. A Request for Continued Examination is being filed concurrently to relieve this application of its finally-rejected status.

The present Amendment revises the independent claims to expressly recite that the test terminals are used for testing a semiconductor chip before the connection terminals are connected to wiring on a board.

Three independent claims are pending in this application – claims 1, 16, and 22. The Office Action rejects all of them for anticipation by patent 6,815,621 to Park et al (hereafter simply “Park”). The Office Action additionally rejects claims 1 and 22 for anticipation by either U.S. patent 5,729,894 to Restorer et al (hereafter simply “Restorer”) or Japanese publication 2000-068403 to Ando. Claim 1, with emphasis added, is set forth below:

A semiconductor package for a semiconductor chip, said semiconductor package having a surface with a plurality of test terminals for use during testing of said semiconductor chip and with a plurality of connection terminals for connection to wiring on a board after testing, said test terminals being electrically isolated from said wiring on said board,

wherein said connection terminals are arranged in a first area at predetermined pitches in a lattice and said test terminals are arranged in a second area at pitches narrower than said predetermined pitches in a lattice.

While the references show a group of terminals with a narrower pitch than other terminals, none of the terminals of any of the references are test terminals. Neither the word “test” nor the word “testing” appears in the text of either the Park reference or the Rostoker reference. The “Patent Abstracts of Japan” English language summary of Ando says nothing about testing, either. Ando’s narrow-pitch solder bumps 13 are present for the purpose of heat dissipation. The narrow-pitch terminals in the Rostoker and Park references are present for the purpose of electrical connection to wiring on a circuit board. None of the references suggest the use of narrow-pitch terminals for testing

before the device is connected to the circuit board. Accordingly, it is respectfully submitted that the references neither anticipate claim 1 or render it obvious.

Independent claim 16 also provides that the test terminals are used for testing before the connection terminals are connected to wiring on a board, and independent claim 22 is similar but recites test leads and connection leads. For reasons along the line discussed above with respect to claim 1, it is respectfully submitted that these claims are likewise patentable over the prior art.

Claims 1 and 22 also provide that the test terminals are electrically isolated from the wiring on the board. This is contrary to Park and Rostoker.

The remaining claims depend from the independent claims discussed above and recite additional limitations to further define the invention. They are therefore patentable along with their independent claims and need not be further discussed.

For the foregoing reasons, it is respectfully submitted that the rejections should be withdrawn. Reconsideration of the application is therefore respectfully requested.

It is noted that an Information Disclosure Statement is being filed concurrently.

Respectfully submitted,

May 10, 2006
Date


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